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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/809,906	03/26/2004	Rahul Surana	008089	7260
			USA/MTCG/PCTRL	
			EXAMINER	
			MCDONALD, SHANTESE L	
			ART UNIT	PAPER NUMBER
			3723	
DATE MAILED: 01/18/2006				

7590 01/18/2006  
Applied Materials, Inc.  
P.O. Box 450A  
Santa Clara, CA 95052

Please find below and/or attached an Office communication concerning this application or proceeding.

**Office Action Summary**

Application No.

10/809,906

Applicant(s)

SURANA ET AL

Examiner

Shantese L. McDonald

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

**Period for Reply**

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

**Status**

- 1) ☐ Responsive to communication(s) filed on 26 March 2004.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

**Disposition of Claims**

- 4) ☒ Claim(s) 1-42 is/are pending in the application.
- 4a) Of the above claim(s) \_\_\_\_\_ is/are withdrawn from consideration.
- 5) ☐ Claim(s) \_\_\_\_\_ is/are allowed.
- 6) ☐ Claim(s) 1-42 is/are rejected.
- 7) ☐ Claim(s) \_\_\_\_\_ is/are objected to.
- 8) ☐ Claim(s) \_\_\_\_\_ are subject to restriction and/or election requirement.

**Application Papers**

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on \_\_\_\_\_ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
- Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

**Priority under 35 U.S.C. § 119**

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some \* c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
  2. ☐ Certified copies of the priority documents have been received in Application No. \_\_\_\_\_.
  3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

\* See the attached detailed Office action for a list of the certified copies not received.

**Attachment(s)**

- |   |   |
|---|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892)   | 4) <input type="checkbox"/> Interview Summary (PTO-413)<br>Paper No(s)/Mail Date. _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948)  | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152)             |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08)<br>Paper No(s)/Mail Date <u>8/11/05, 10/8/04</u> . | 6) <input type="checkbox"/> Other: _____  |

IDS (cont) 8/11/04, 8/16/04, 12/7/04

## DETAILED ACTION

### ***Claim Rejections - 35 USC § 102***

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 1-42 are rejected under 35 U.S.C. 102(e) as being anticipated by

Redeker et al.

Redeker et al. teaches a method for qualifying a semiconductor manufacturing tool, by using a computer readable medium, 90, comprising transferring a single patterned wafer to a bulk removal polishing platen, (col. 7, lines 31-63), measuring in situ bulk removal polishing platen characteristics, which include polishing rate, nonuniformity and defectivity, from the wafer during the processing by the bulk removal polishing platen, using an eddy current measuring sensor implemented at the bulk removal polishing platen, (col. 9, lines 57-59), qualifying the bulk removal polishing platen by adjusting one or more parameters of a recipe in accordance with the one or more bulk removal polishing platen characteristics, (col. 10, lines 46-61). Redeker et al. also teaches transferring the wafer to a copper clearing platen, measuring in situ, using a laser interferometer, (col. 8, lines 57-65 and col. 11, lines 19-20), copper clearing platen qualification characteristics from the wafer during processing by the copper clearing platen, and qualify the copper clearing platen by adjusting one or more parameters of the recipe, (col. 10, line 62-col. 11, line 54), and transferring a wafer to a barrier removal polishing platen, measuring in situ, using an optical sensor, (col. 11,

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lines 64-65), barrier removal platen qualification characteristics and qualifying the barrier removal polishing platen by adjusting one or more parameters of the recipe, (col. 11, lines 55-67). Redeker also teaches measuring in situ a defectivity from the wafer and qualifying the tool for the defectivity by adjusting one or more parameters of the recipe, (col. 10, lines 13-34).

### ***Conclusion***

The prior art made of record and not relied upon is considered pertinent to applicant's disclosure. Chen et al. and Kim et al. were cited to show other examples of polishing methods.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Shantese L. McDonald whose telephone number is (571) 272-4486. The examiner can normally be reached on 8:00 a.m. - 4:30 p.m..

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Joseph Hail can be reached on (571) 272-4485. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).



S.L.M.  
December 12, 2005

Joseph J. Mail, III  
Supervisory Patent Examiner  
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